

# HiPerFET™

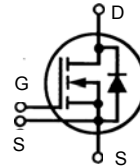
## Power MOSFETs

### Single Die MOSFET

N-Channel Enhancement Mode  
Avalanche Rated, High dv/dt, Low  $t_{rr}$

Preliminary Data

## IXFE 39N90



$$V_{DSS} = 900 \text{ V}$$

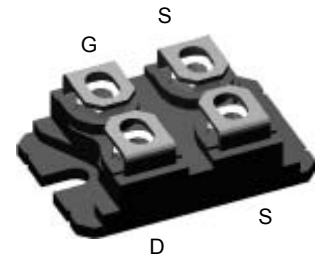
$$I_{D25} = 34 \text{ A}$$

$$R_{DS(on)} = 220 \text{ m}\Omega$$

$$t \leq \text{ns}$$

Symbol	Test Conditions	Maximum Ratings	
$V_{DSS}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	900	V
$V_{DGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ ; $R_{GS} = 1 \text{ M}\Omega$	900	V
$V_{GS}$	Continuous	$\pm 20$	V
$V_{GSM}$	Transient	$\pm 30$	V
$I_{D25}$	$T_C = 25^\circ\text{C}$ , Chip capability	34	A
$I_{DM}$	$T_C = 25^\circ\text{C}$ , Note 1	154	A
$I_{AR}$	$T_C = 25^\circ\text{C}$	39	A
$E_{AR}$	$T_C = 25^\circ\text{C}$	64	mJ
$E_{AS}$	$T_C = 25^\circ\text{C}$	4	J
dv/dt	$I_S \leq I_{DM}$ , di/dt $\leq 100 \text{ A}/\mu\text{s}$ , $V_{DD} \leq V_{DSS}$ $T_J \leq 150^\circ\text{C}$ , $R_G = 2 \Omega$	5	V/ns
$P_D$	$T_C = 25^\circ\text{C}$	580	W
$T_J$		-40 ... +150	$^\circ\text{C}$
$T_{JM}$		150	$^\circ\text{C}$
$T_{stg}$		-40 ... +150	$^\circ\text{C}$
$V_{ISOL}$	50/60 Hz, RMS $t = 1 \text{ min}$ $I_{ISOL} \leq 1 \text{ mA}$ $t = 1 \text{ s}$	2500 3000	V~ V~
$M_d$	Mounting torque Terminal connection torque	1.5/13	Nm/lb.in. Nm/lb.in.

### ISOPLUS 227™ (IXFE)



G = Gate  
S = Source  
D = Drain

Either Source terminal at miniBLOC can be used as Main or Kelvin Source

### Features

- Conforms to SOT-227B outline
- Low  $R_{DS(on)}$  HDMOS™ process
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
- Fast intrinsic Rectifier

### Applications

- DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- Temperature and lighting controls

### Advantages

- Low cost
- Easy to mount
- Space savings
- High power density

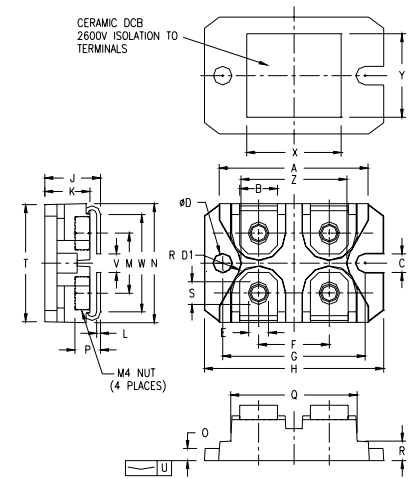
Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$V_{DSS}$	$V_{GS} = 0 \text{ V}$ , $I_D = 3 \text{ mA}$	900		V
$V_{GH(th)}$	$V_{DS} = V_{GS}$ , $I_D = 8 \text{ mA}$	2.5		V
$I_{GSS}$	$V_{GS} = \pm 20 \text{ V}_{DC}$ , $V_{DS} = 0$			$\pm 200 \text{ nA}$
$I_{DSS}$	$V_{DS} = V_{DSS}$ , $T_J = 25^\circ\text{C}$ $V_{GS} = 0 \text{ V}$ , $T_J = 125^\circ\text{C}$			100 $\mu\text{A}$ 2 mA
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$ , $I_D = I_T$ Notes 2, 3			220 m $\Omega$

Symbol	Test Conditions	Characteristic Values ( $T_j = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$g_{fs}$	$V_{DS} = 15\text{ V}; I_D = I_T$ , Note 2	30	45	S
$C_{iss}$	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$		13400	pF
$C_{oss}$			1230	pF
$C_{rss}$			320	pF
$t_{d(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = I_T$ $R_G = 1\ \Omega$ (External),		45	ns
$t_r$			68	ns
$t_{d(off)}$			125	ns
$t_f$			30	ns
$Q_{g(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = I_T$		375	nC
$Q_{gs}$			75	nC
$Q_{gd}$			190	nC
$R_{thJC}$			0.22	K/W
$R_{thCK}$			0.07	K/W

Source-Drain Diode		Characteristic Values ( $T_j = 25^\circ\text{C}$ , unless otherwise specified)		
Symbol	Test Conditions	min.	typ.	max.
$I_s$	$V_{GS} = 0\text{ V}$			39 A
$I_{SM}$	Repetitive; Note 1			154 A
$V_{SD}$	$I_F = I_s, V_{GS} = 0\text{ V}$ , Note 2			1.3 V
$t_{rr}$	$I_F = 25\text{ A}, -di/dt = 100\text{ A}/\mu\text{s}, V_R = 100\text{ V}$			250 ns
$Q_{RM}$			2	$\mu\text{C}$
$I_{RM}$			9	A

- Notes: 1. Pulse width limited by  $T_{JM}$ .  
 2. Pulse test,  $t \leq 300\text{ ms}$ , duty cycle  $d \leq 2\%$ .  
 3.  $I_T$  Test current:  $I_T = 19.5\text{ A}$

### ISOPLUS-227 B



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.240	1.270	31.50	32.26
B	.310	.330	7.87	8.38
C	.155	.165	3.94	4.19
D	.155	.165	3.94	4.19
D1	.150	.157	3.81	3.98
E	.160	.168	4.06	4.27
F	.587	.595	14.91	15.11
G	1.186	1.193	30.12	30.30
H	1.489	1.505	37.80	38.23
J	.465	.481	11.81	12.22
K	.370	.380	9.40	9.65
L	.030	.033	0.76	0.84
M	.496	.506	12.60	12.85
N	.990	1.001	25.15	25.42
O	.100	.105	2.54	2.67
P	.195	.235	4.95	5.97
Q	1.045	1.059	26.54	26.90
R	.160	.170	4.06	4.32
S	.186	.191	4.72	4.85
T	.968	.987	24.59	25.07
U	-.001	.002	-0.03	0.05
V	.130	.160	3.30	4.06
W	.780	.830	19.81	21.08
X	.770	.810	19.56	20.57
Y	.680	.720	17.27	18.29
Z	.885	.892	22.48	22.66

Please see IXFN39N90 data sheet for characteristic curves.

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,881,106 5,017,508 5,049,961 5,187,117 5,486,715 6,306,728B1  
 4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025